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10/ April  
(N.E.)  
F.22.03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/004,172  
Filing Date ..... October 9, 2001  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-1839  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding  
Frames

**RESPONSE TO FEBRUARY 11, 2003 OFFICE ACTION**

To: Box Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: D. Brent Kenady  
Tel. 509-624-4276; Fax 509-838-3424  
Wells St. John P.S.  
601 West First Avenue, Suite 1300  
Spokane, WA 99201-3828

Responsive to the Office Action dated February 11, 2003, Applicant  
amends and remarks as follows:

**AMENDMENTS**

**RECEIVED**

**APR 21 2003**

TECHNOLOGY CENTER R3700